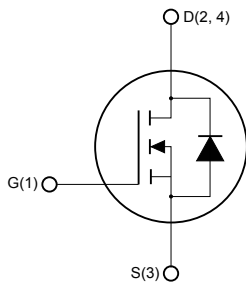
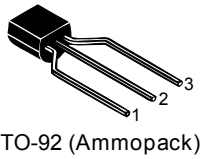


N-channel 600 V, 7.3 Ω typ., 0.4 A SuperMESH™ Power MOSFETs in a SOT-223 and TO-92 packages



Int_schem_nTnZ_SOT_223

Features

Order code	V_{DS}	$R_{DS(on)}$ max.	I_D	Package
STN1HNK60	600 V	8.5 Ω	0.4 A	SOT-223
STQ1HNK60R-AP				TO-92

- Extremely high dv/dt capability
- 100% avalanche tested
- Gate charge minimized

Applications

- Switching applications

Description

These high-voltage devices are Zener-protected N-channel Power MOSFETs developed using the SuperMESH™ technology by STMicroelectronics, an optimization of the well-established PowerMESH™. In addition to a significant reduction in on-resistance, these devices are designed to ensure a high level of dv/dt capability for the most demanding applications.

Product status

STN1HNK60

STQ1HNK60R-AP

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value		Unit
		SOT-223	TO-92	
V_{DS}	Drain-source voltage	600		V
V_{DGR}	Drain-gate voltage ($R_{GS} = 20\text{ k}\Omega$)	600		V
V_{GS}	Gate- source voltage	± 30		V
I_D	Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$	0.4		A
I_D	Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$	0.25		A
$I_{DM}^{(1)}$	Drain current (pulsed)	1.6		A
P_{TOT}	Total dissipation at $T_C = 25\text{ }^\circ\text{C}$	3.3	3	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	3		V/ns
T_j	Operating junction temperature range	-55 to 150		$^\circ\text{C}$
T_{stg}	Storage temperature range			

1. Pulse width limited by safe operating area.
2. $I_{SD} \leq 0.4\text{ A}$, $di/dt \leq 100\text{ A}/\mu\text{s}$, $V_{DD} \leq V_{(BR)DSS}$.

Table 2. Thermal data

Symbol	Parameter	Value		Unit
		SOT-223	TO-92	
$R_{thj-amb}$	Thermal resistance junction-ambient		120	$^\circ\text{C}/\text{W}$
$R_{thj-lead}$	Thermal resistance junction-lead		40	$^\circ\text{C}/\text{W}$
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb	37.87		$^\circ\text{C}/\text{W}$

1. When mounted on FR-4 board of 1 in^2 , 2 oz Cu, $t < 10\text{ s}$.

Table 3. Avalanche characteristics

Symbol	Parameter	Value	Unit
I_{AR}	Avalanche current, repetitive or not-repetitive (pulse width limited by $T_j\text{ Max}$)	0.4	A
E_{AS}	Single pulse avalanche energy (starting $T_j = 25\text{ }^\circ\text{C}$, $I_D = I_{AR}$, $V_{DD} = 50\text{ V}$)	25	mJ

2 Electrical characteristics

($T_{CASE} = 25\text{ °C}$ unless otherwise specified)

Table 4. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 1\text{ mA}, V_{GS} = 0\text{ V}$	600			V
I_{DSS}	Zero gate voltage drain current	$V_{GS} = 0\text{ V}, V_{DS} = 600\text{ V}$			1	μA
		$V_{GS} = 0\text{ V}, V_{DS} = 600\text{ V}, T_C = 125\text{ °C}^{(1)}$			50	μA
I_{GSS}	Gate body leakage current	$V_{DS} = 0\text{ V}, V_{GS} = \pm 30\text{ V}$			± 100	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	2.25	3	3.7	V
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 10\text{ V}, I_D = 0.5\text{ A}$		7.3	8.5	Ω

1. Defined by design, not subject to production test.

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{DS} = 25\text{ V}, f = 1\text{ MHz}, V_{GS} = 0\text{ V}$	-	156		μF
C_{oss}	Output capacitance			23.5		
C_{rss}	Reverse transfer capacitance			3.8		
Q_g	Total gate charge	$V_{DD} = 480\text{ V}, I_D = 1\text{ A}, V_{GS} = 0\text{ to }10\text{ V}$ (see Figure 16. Test circuit for gate charge behavior)	-	7	10	nC
Q_{gs}	Gate-source charge			1.1		
Q_{gd}	Gate-drain charge			3.7		

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 300\text{ V}, I_D = 0.5\text{ A},$ $R_G = 4.7\text{ }\Omega, V_{GS} = 10\text{ V}$ (see Figure 15. Test circuit for resistive load switching times and Figure 20. Switching time waveform)	-	6.5	-	ns
t_r	Rise time			5		
$t_{d(off)}$	Turn-off delay time			19		
t_f	Fall time			25		

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current				0.4	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		1.6	
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 0.4 \text{ A}$, $V_{GS} = 0 \text{ V}$	-		1.6	V
t_{rr}	Reverse recovery time	$I_{SD} = 1.0 \text{ A}$, $di/dt = 100 \text{ A}/\mu\text{s}$		140		ns
Q_{rr}	Reverse recovery charge	$V_{DD} = 25 \text{ V}$ (see Figure 17. Test circuit for inductive load switching and diode recovery times)	-	240		nC
I_{RRM}	Reverse recovery current			3.3		A
t_{rr}	Reverse recovery time	$I_{SD} = 1.0 \text{ A}$, $di/dt = 100 \text{ A}/\mu\text{s}$		229		ns
Q_{rr}	Reverse recovery charge	$V_{DD} = 25 \text{ V}$, $T_J = 150 \text{ }^\circ\text{C}$ (see Figure 17. Test circuit for inductive load switching and diode recovery times)	-	377		nC
I_{RRM}	Reverse recovery current			3.3		A

1. Pulse width limited by safe operating area.
2. Pulsed: pulse duration = 300 μs , duty cycle 1.5%.

2.1 Electrical characteristics curves

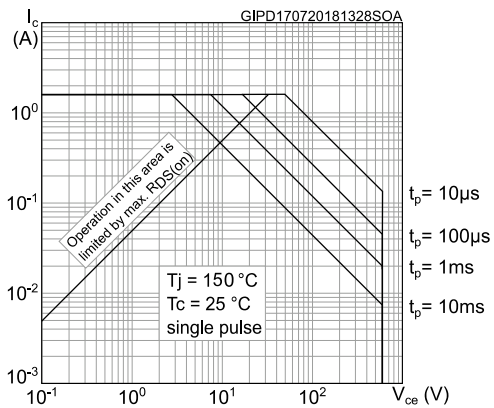
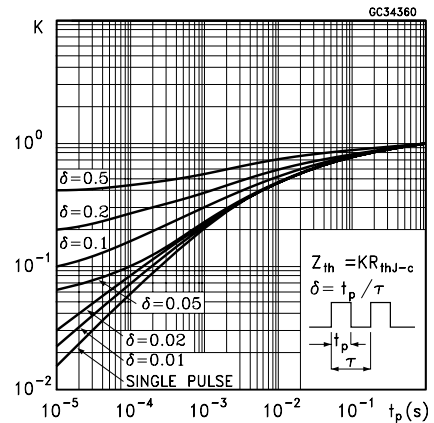
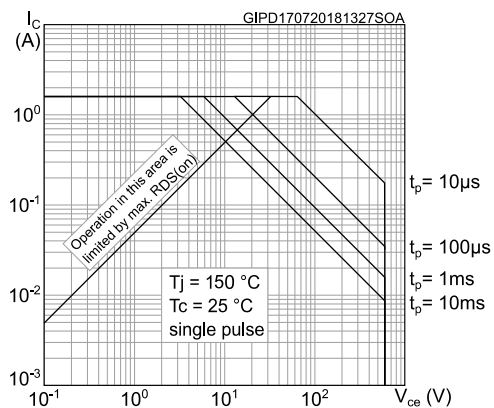
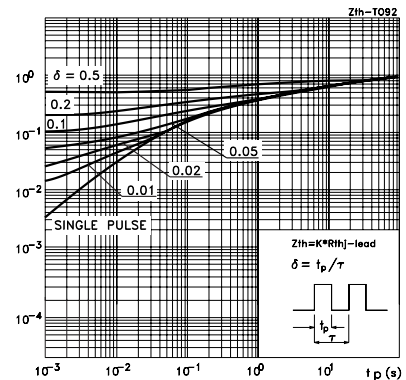
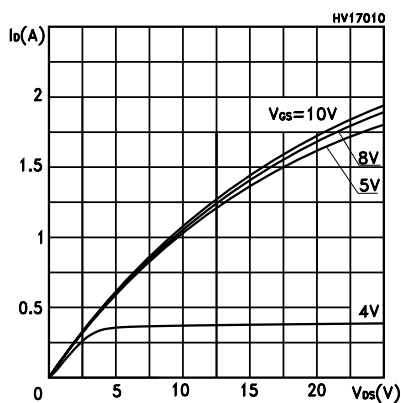
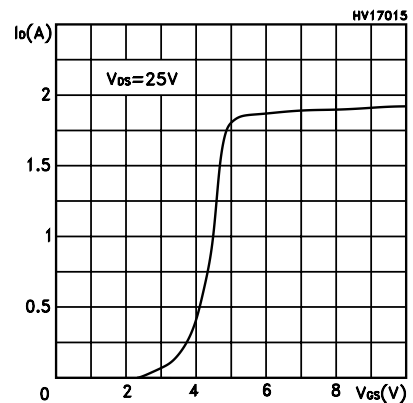
Figure 1. Safe operating area for SOT-223

Figure 2. Thermal impedance for SOT-223

Figure 3. Safe operating area for TO-92

Figure 4. Thermal impedance for TO-92

Figure 5. Output characteristics

Figure 6. Transfer characteristics


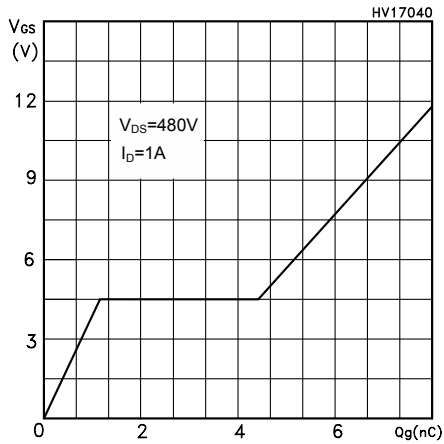
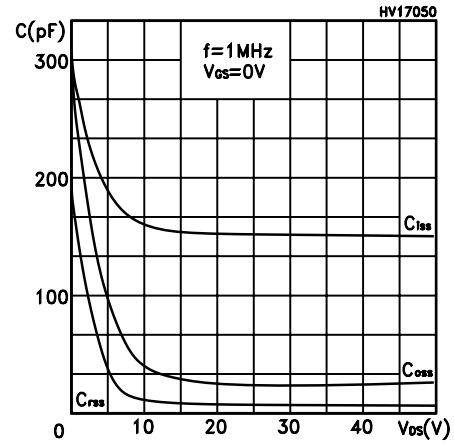
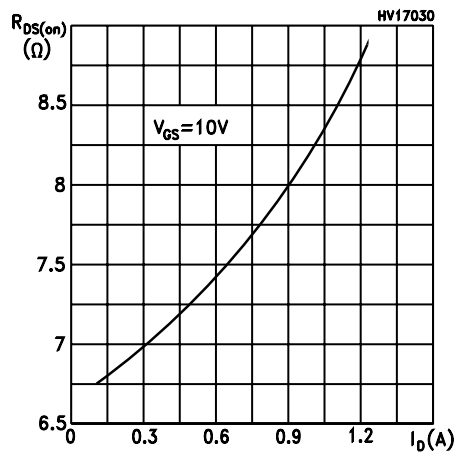
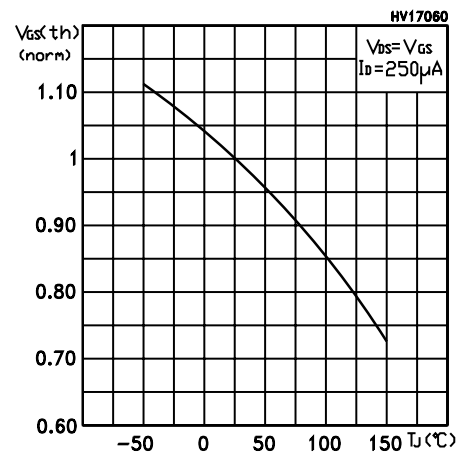
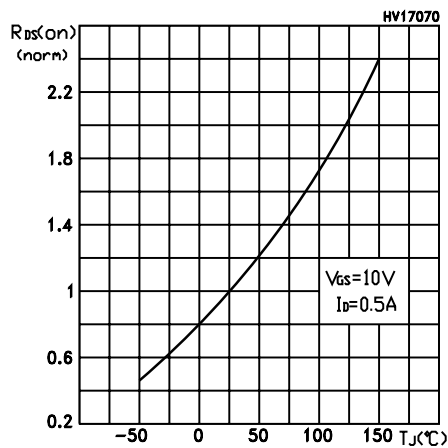
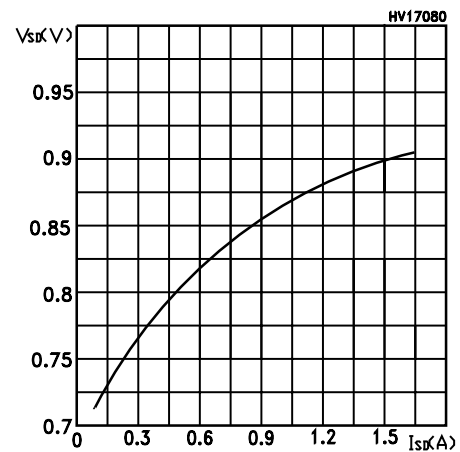
Figure 7. Gate charge vs gate-source voltage

Figure 8. Capacitance variations

Figure 9. Static drain-source on-resistance

Figure 10. Normalized gate threshold voltage vs temperature

Figure 11. Normalized on-resistance vs temperature

Figure 12. Source-drain forward characteristics


Figure 13. Normalized $V_{(BR)DSS}$ vs Temperature

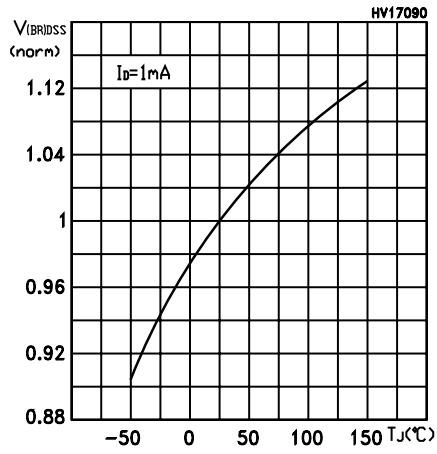
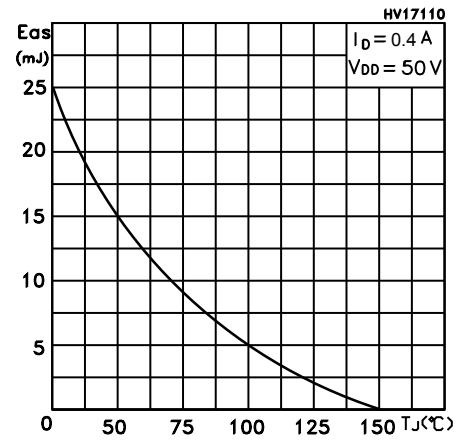
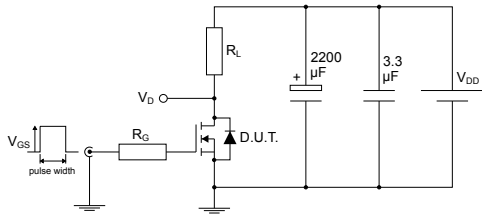


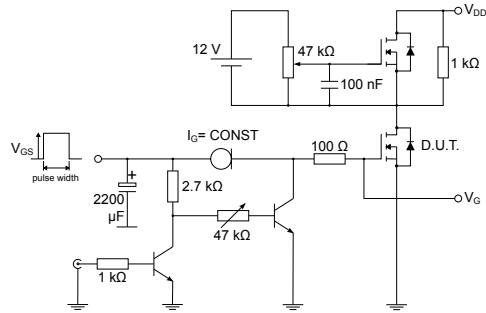
Figure 14. Maximum avalanche energy vs temperature



3 Test circuits

Figure 15. Test circuit for resistive load switching times


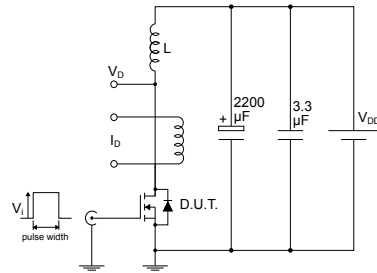
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Figure 16. Test circuit for gate charge behavior


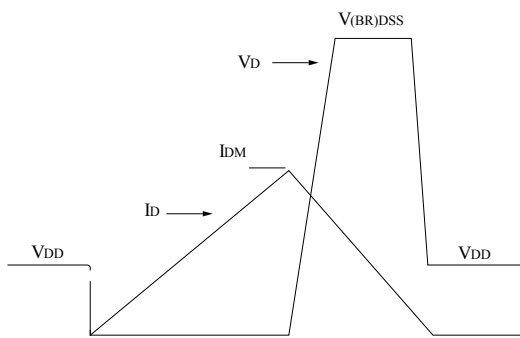
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Figure 17. Test circuit for inductive load switching and diode recovery times

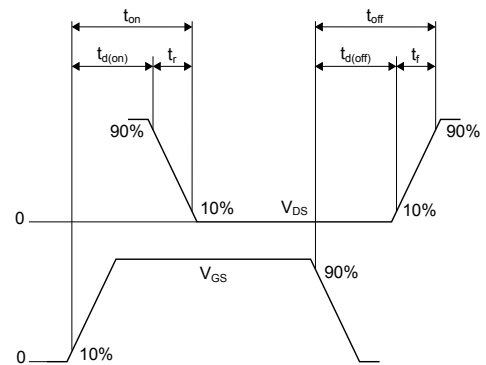

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Figure 18. Unclamped inductive load test circuit


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Figure 19. Unclamped inductive waveform


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Figure 20. Switching time waveform


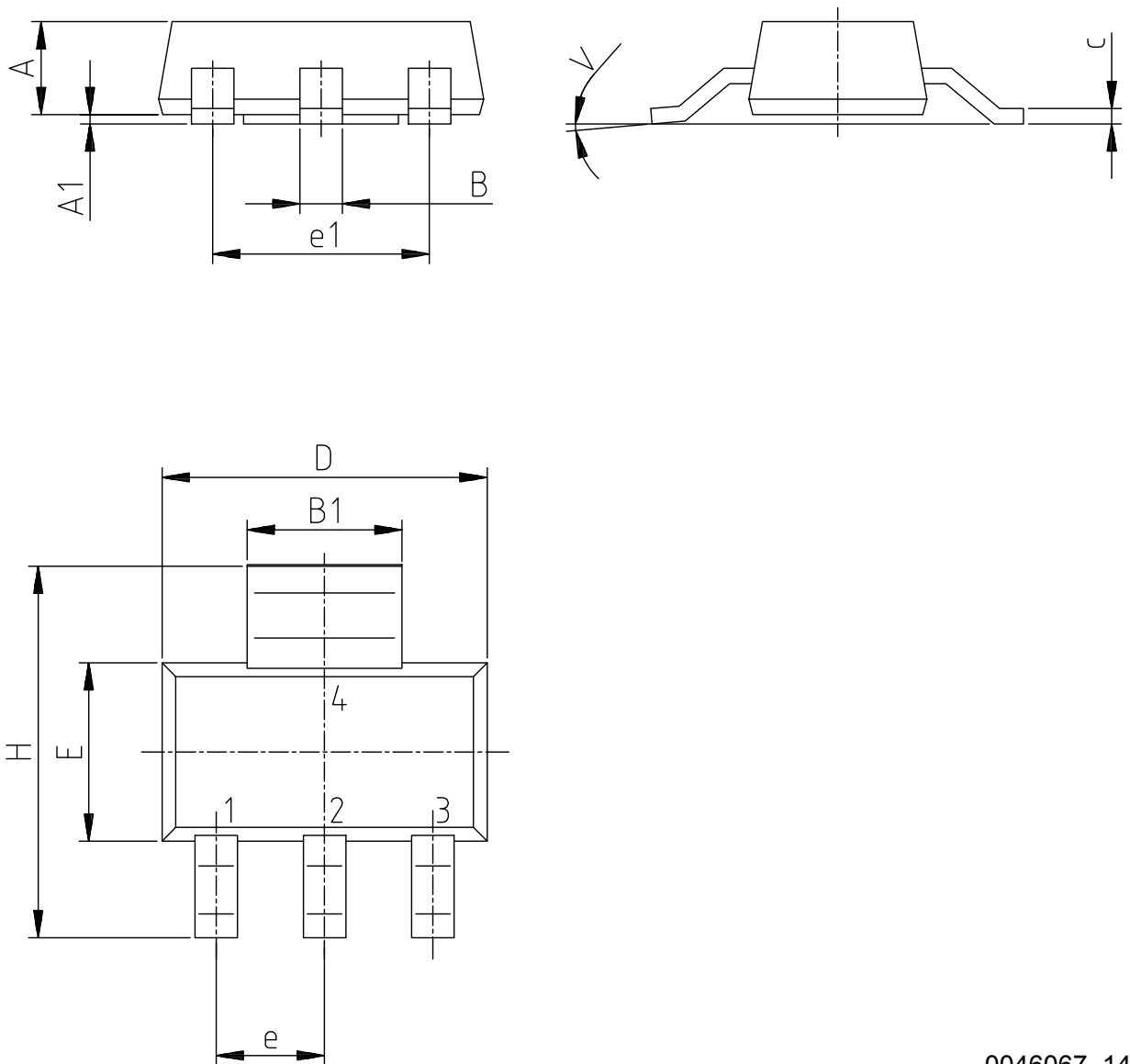
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4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 SOT-223 package information

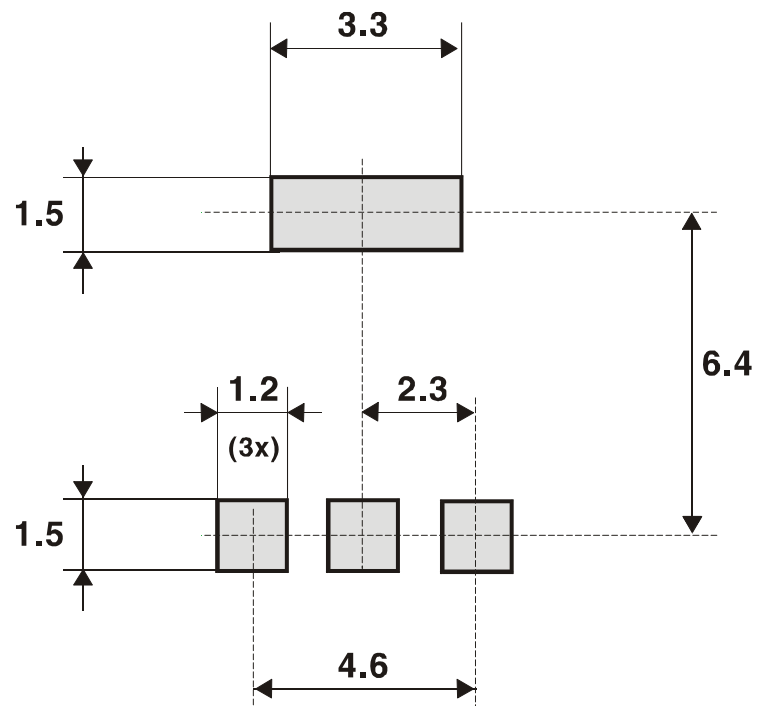
Figure 21. SOT-223 package outline



0046067_14

Table 8. SOT-223 package mechanical data

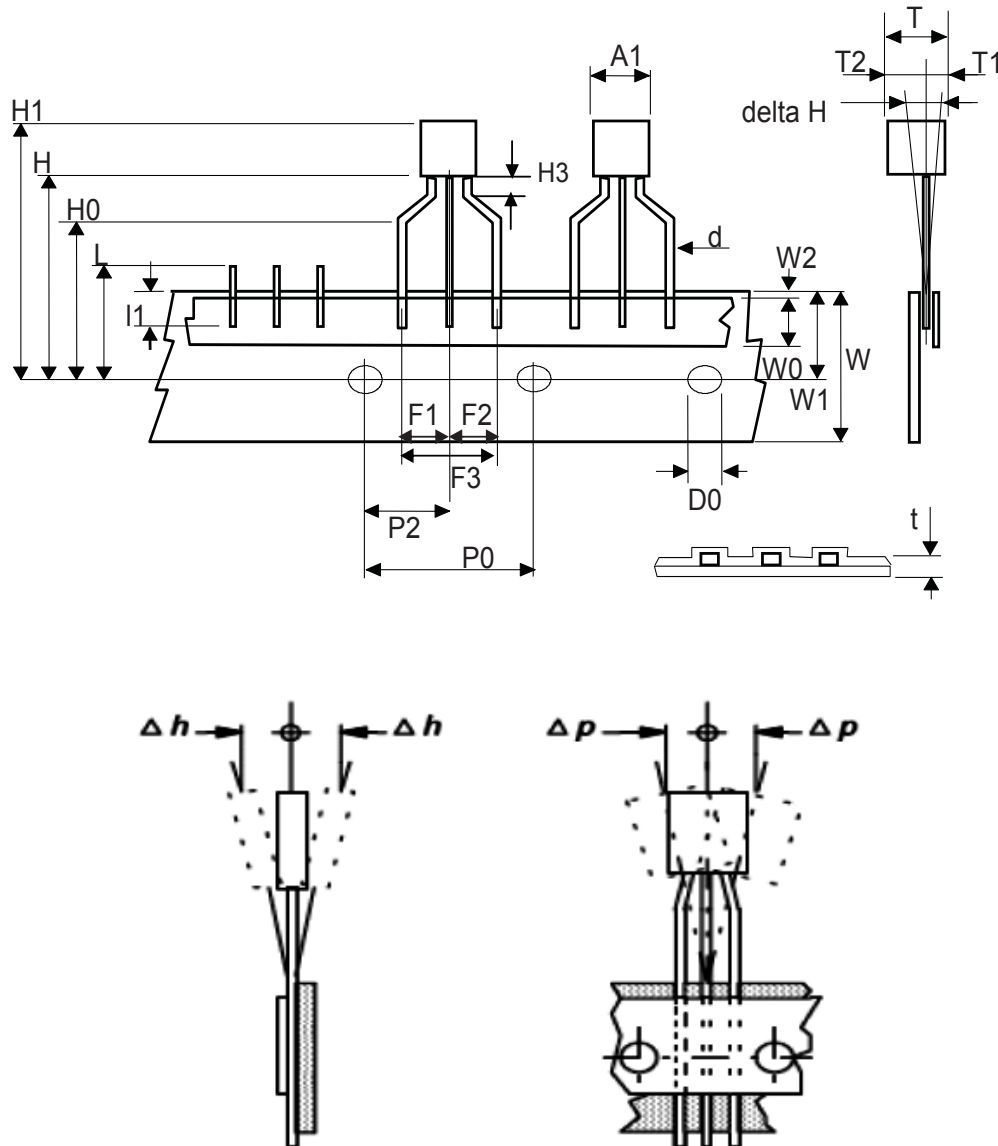
Dim.	mm		
	Min.	Typ.	Max.
A			1.8
A1	0.02		0.1
B	0.6	0.7	0.85
B1	2.9	3	3.15
c	0.24	0.26	0.35
D	6.3	6.5	6.7
e		2.3	
e1		4.6	
E	3.3	3.5	3.7
H	6.7	7.0	7.3
V			10°

Figure 22. SOT-223 recommended footprint (dimensions are in mm)


0046067

4.2 TO-92 Ammopack package information

Figure 23. TO-92 Ammopack package outline



0050910_Rev_22

Table 9. TO-92 Ammopack mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A1			4.80
T			3.80
T1			1.60
T2			2.30
d	0.45	0.47	0.48
P0	12.50	12.70	12.90
P2	5.65	6.35	7.05
F1, F2	2.40	2.50	2.94
F3	4.98	5.08	5.48
delta H	-2.00		2.00
W	17.50	18.00	19.00
W0	5.50	6.00	6.50
W1	8.50	9.00	9.25
W2			0.50
H		18.50	21.00
H0	15.50	16.00	18.20
H1		25.00	27.00
H3	0.50	1.00	2.00
D0	3.80	4.00	4.20
t			0.90
L			11.00
l1	3.00		
delta P	-1.00		1.00

5 Ordering information

Table 10. Order codes

Order code	Marking	Package	Packing
STN1HNK60	N1HNK60	SOT-223	Tape and reel
STQ1HNK60R-AP	1HNK60R	TO-92	Ammopak

Revision history

Table 11. Document revision history

Date	Version	Changes
20-Aug-2018	1	Initial release.

Contents

1	Electrical ratings	2
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